

Structural characteristics and interfacial reactions of low dielectric constant porous polysilazane for Cu metallization

Wang JH, Liu PT, Chang TS, Chang TC, Chen LJ.
Thin Solid Films
2004; 469-470(SPEC. ISS.):393-397

ARTICLE IDENTIFIERS

DOI: 10.1016/j.tsf.2004.09.014

PMID: unavailable

PMCID: not available

JOURNAL IDENTIFIERS

LCCN: not available

pISSN: 0040-6090

eISSN: not available

OCLC ID: not available

CONS ID: not available

US National Library of Medicine ID: not available

This article was identified from a query of the SafetyLit database.